

ABSTRACT OF THE DISCLOSURE

APPARATUS FOR NONDESTRUCTIVELY REMOVING LAYOUT PATTERN FROM WAFER SURFACE

5 An apparatus for removing layout pattern from a top metal layer of a defective wafer includes a removal device including horizontal sand spraying units and a blowing unit having a first sub-unit above the sand spraying units and a second sub-unit aligned with the first sub-unit and below the sand spraying units; and an endless, continuous conveyor for carrying the wafer from a wafer feed device and
10 transferring the wafer to a wafer collecting device by passing a space between the sand spraying units and the second sub-unit. The sand spraying units are adapted to horizontally spray sand, and the first sub-unit is adapted to blow air toward the second sub-unit for sucking the sand onto a top of the passing wafer to smash the layout pattern in the metal layer to ashes with a remaining portion of the wafer being
15 undamaged to be adapted to reuse or recycle.

Selected Drawing: Fig. 1